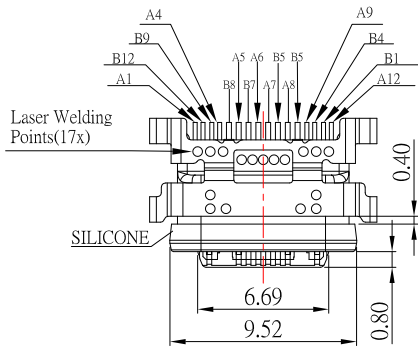


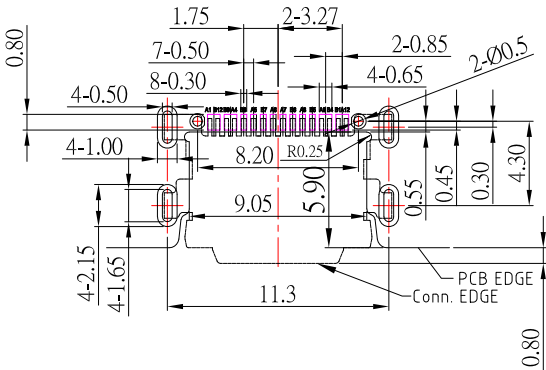
IPX8



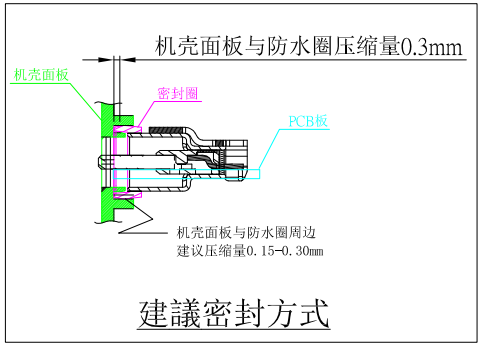
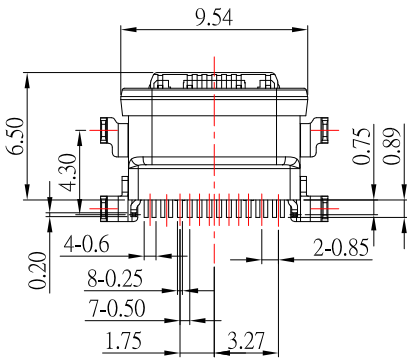
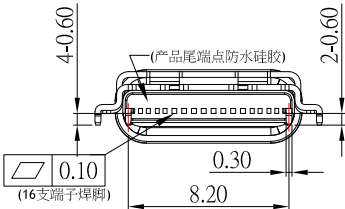
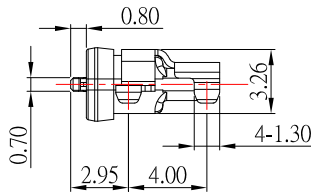
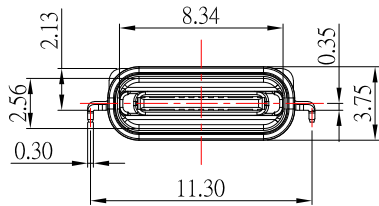
SBC-WP160M4-20x-S175

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LAYOUT



SPECIFICATIONS

Electrical:

- 1.Rating: 5.0V , 3.0 A
- 2.Contact Resistance: 40 mΩ Max
- 3.Insulation Resistance: 100 MΩ Min

Mechanical:

- 1.Connector Mate and Unmate Force
 - 1.1 Mate force: 5~20 N
 - 1.2 Unmate force: 8~20 N

Material:

- 1.Housing: PA9T
- 2.Contact: C18400
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer



TOLERANCE UNLESS OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY:

Jack Lu

DATE

11/19/25

MAT'L

FINISH

SCALE

SHEET NO.

TITLE

MODLE

DWG NO.

PART NO.

CONNECTOR

USB TYPE C 2.0 沉板 2.13mm 防水型IPX8

SBC-WP160M4-20x-S175

SBC-WP160M4-20x-S175

SIZE

A4

VER

R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	新增密封方式	Jack	111925